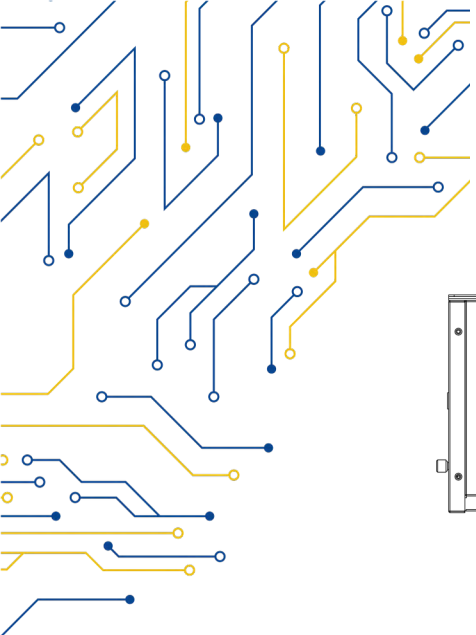




FAN-COOLED INDUSTRIAL BOX PC

MECHANICAL FEATURES	
DIMENSIONS	330 x 196 x 406 mm
CHASSIS	SGCC with forced ventilation
COLOUR	Black
MOUNTING	Desktop
ENVIRONMENTAL FEATURES	
STANDARD CERTIFICATIONS	CE / FCC Class A
OPERATING TEMPERATURE	0°~50°C w/ 0.7m/s airflow
STORAGE TEMPERATURE	-20°~75°C
HUMIDITY	10%~85% Humidity, non-condensing
OTHERS	
WATCHDOG TIMER	From Super I/O to drag RESETCON# 256 Segments, 0, 1, 2, ...255sec
TPM	TPM 2.0 onboard
NOTES	
RAM, CPU and SSD must be specified in the inquiry	

TYPE	FANNED BOX PC
SYSTEM	
CPU	Intel® Core™ 12th/13th Gen. 35W
CHIPSET	Intel® Q670E
BIOS	AMI SPI 256Mbit BIOS
RAM	4x 288-pin SO-DIMM DDR4 3200 MHz 128GB (32 GB per DIMM)
GPU	Intel® UHD Graphics Engines (Supports Triple Display)
OPERATING SYSTEM	Windows 10/11, Linux
STORAGE	
SATA	4x SATA 600Mb/s
RAID	Intel® SATA RAID 0/1/5/10
I/O	
USB	2x USB 3.2 Gen2, 2x USB 3.2 Gen1, 4x USB 2.0
SERIAL PORTS	5x RS232, 1x RS232/422/485
VIDEO (TRIPLE DISPLAY)	1x HDMI, 1x DP, 1x VGA
AUDIO	3x (Mic-In, Line-In, Line-Out), Realtek ALC897/AL887
ETHERNET	1x RJ45 LAN1 Intel® I219LM (PHY) with 10/100/1000 Mbps 1x RJ45 LAN2 Intel® I210-AT with 10/100/1000 Mbps
EXPANSION SLOTS	
PCIe	3x PCIe x4 Gen3 1x PCIe x8 Gen3 (x4 link) 1x PCIe x16 Gen4
PCI	2x PCI
M.2	1x M.2 (Key E, 2230) with PCIe x1, USB 2.0 and CNVi for Wireless 1x M.2 (Key B, 3042/3052) with PCIe x1, USB3.2 Gen1, USB 2.0 and SIM for 4G/5G
POWER REQUIREMENTS	
POWER INPUT	110~230V AC



HSB-788

